

## **Characteristics**

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value	Unit		
I <sub>T(RMS)</sub>	RMS on-state current (full sine wave)	D <sup>2</sup> PAK, TO-220AB	T <sub>c</sub> = 130 °C	16	А
		TO-220AB Ins.	T <sub>c</sub> = 113 °C		
l-o	Non repetitive surge peak on-state current (full cycle,	f = 50 Hz	t = 20 ms	160 168 169	
I <sub>TSM</sub>	T <sub>j</sub> initial = 25 °C)	f = 60 Hz t = 16.7 ms		168	Α
I <sup>2</sup> t	I <sup>2</sup> t value for fusing	t <sub>p</sub> = 10 ms	169	A <sup>2</sup> s	
dl/dt	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , tr $\leq 100 \text{ ns}$ , f = 100 Hz		T <sub>j</sub> = 150 °C	100	A/µs
V <sub>DSM</sub> / V <sub>RSM</sub>	Non Repetitive peak off-state voltage	T <sub>j</sub> = 25 °C		V	
I <sub>GM</sub>	Peak gate current	T <sub>j</sub> = 150 °C	4	Α	
P <sub>G(AV)</sub>	Average gate power dissipation	1	W		
T <sub>stg</sub>	Storage temperature range	-40 to +150	°C		
T <sub>j</sub>	Operating junction temperature range	-40 to +150	°C		

Table 2. Electrical characteristics ( $T_j$  = 25 °C, unless otherwise specified)

Symbol	Test conditions	Quadrants		Va	Value	
Symbol	rest conditions	Quadrants		T1635H	T1650H	Unit
I <sub>GT</sub> <sup>(1)</sup>	$V_D = 12 \text{ V}, R_L = 33 \Omega$	1 - 11 - 111	Max.	35	50	mA
V <sub>GT</sub>	VD - 12 V, NL - 33 12	Max.		1.0		V
$V_{GD}$	$V_D = V_{DRM}$ , $R_L = 3.3 \text{ k}\Omega$	1 - 11 - 111	Min.	0.15		V
l <sub>1</sub>	I <sub>G</sub> = 1.2 x I <sub>GT</sub>	1 - 111	Max.	50	90	mA
'L	IG = 1.2 × IG	II	Max.	80	110	
I <sub>H</sub> (2)	I <sub>T</sub> = 500 mA, gate open		Max.	35	75	mA
dV/dt (2)	V <sub>D</sub> = 2/3 x V <sub>DRM</sub> , gate open	T <sub>j</sub> = 150 °C	Min.	1000	1500	V/µs
(dl/dt)c (2)	Without snubber	T <sub>j</sub> = 150 °C	Min.	21	28	A/ms

<sup>1.</sup> Minimum  $I_{GT}$  is guaranteed at 20% of  $I_{GT}$  max.

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<sup>2.</sup> For both polarities of A2 referenced to A1.



**Table 3. Static characteristics** 

Symbol	Test conditions		Value	Unit	
V <sub>T</sub> <sup>(1)</sup>	$I_{TM} = 23 \text{ A}, t_p = 380  \mu\text{s}$	T <sub>j</sub> = 25 °C	Max.	1.5	V
V <sub>TO</sub> (1)	Threshold voltage $T_j$ = 150 °C		Max.	0.80	V
R <sub>D</sub> (1)	Dynamic resistance	T <sub>j</sub> = 150 °C	Max.	23	mΩ
I <sub>DRM</sub> /	V <sub>DRM</sub> = V <sub>RRM</sub>	T <sub>j</sub> = 25 °C	Max.	5	μA
	VDRM - VRRM	T <sub>j</sub> = 150°C		4.1	mA
	V <sub>D</sub> = V <sub>R</sub> = 400 V, peak voltage	T <sub>j</sub> = 150 °C	Max.	3.5	mA
	V <sub>D</sub> = V <sub>R</sub> = 200 V, peak voltage	T <sub>j</sub> = 150 °C	Max.	3.0	IIIA

- 1. For both polarities of A2 referenced to A1.
- 2.  $t_p = 380 \, \mu s$

**Table 4. Thermal resistance** 

Symbol	Parameter				
R <sub>th(j-c)</sub>	Junction to case (AC)	D <sup>2</sup> PAK, TO-220AB	1.15	°C/W	
		TO-220AB Ins.	2.1		
R <sub>th(j-a)</sub>	Junction to ambient (S <sub>cu</sub> = 2 cm <sup>2</sup> )	D <sup>2</sup> PAK, TO-220AB	45	°C/W	
,	Junction to ambient	TO-220AB Ins.	60		



### 1.1 Characteristics (curves)

Figure 1. Maximum power dissipation versus on-state RMS current

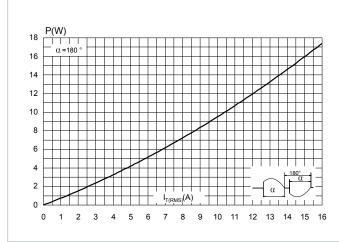


Figure 2. On-state RMS current versus case temperature

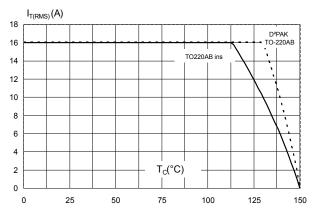


Figure 3. On-state RMS current versus ambient temperature

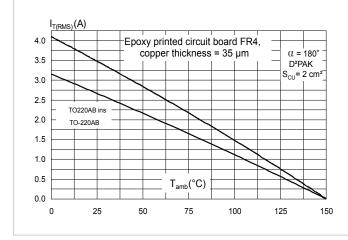
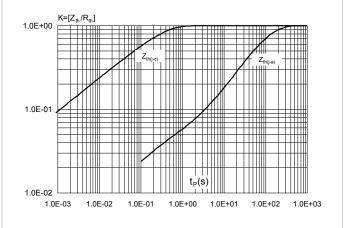


Figure 4. Variation of thermal impedance versus pulse duration



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Figure 5. On-state characteristics (maximum values)  $I_{TM}(A)$ 1000 100 T<sub>i</sub>=150 °C T<sub>i</sub>=25 °C 10  $V_{t0}^{J} = 0.80 \text{ V}$   $R_{d} = 23 \text{ m}\Omega$  $V_{TM}(V)$ 0.5 0.0 1.0 1.5 2.0 2.5 3.0 4.0 4.5

Figure 6. Surge peak on-state current versus number of cycles I<sub>TSM</sub> (A) 180 160 Non repetitive T<sub>i</sub> initial = 25 °C 140 120 100 80 60 40 20 Number of cycles 0 10 100 1000

Figure 7. Non repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10 \text{ ms}$ 

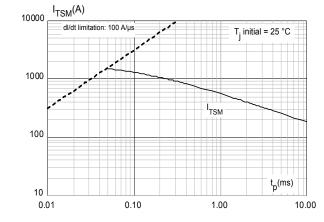


Figure 8. Relative variation of I<sub>GT</sub>,I<sub>H</sub>, I<sub>L</sub> vs junction

temperature (typical values)

Figure 9. Relative variation of critical rate of decrease of main current (dl/dt)c versus reapplied (dV/dt)c

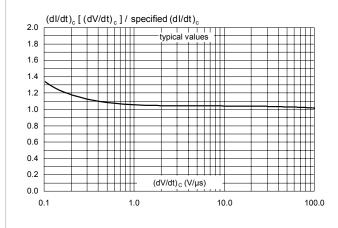
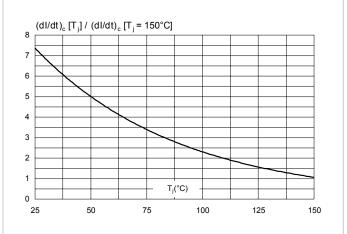


Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature



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Figure 11. Leakage current versus junction temperature for different values of blocking voltage (typical values)

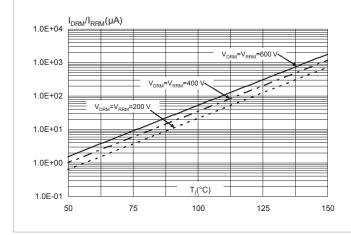
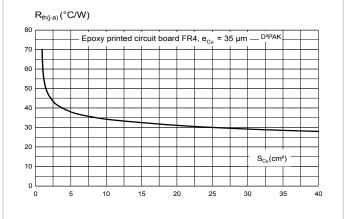


Figure 12. Thermal resistance junction to ambient versus copper surface under tab





# 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

#### 2.1 TO-220AB package information

- Molding compound resin is halogen-free and meets flammability standard UL94 level 0
- · Lead-free package leads finishing
- ECOPACK2 compliant
- Recommended torque: 0.4 to 0.6 N.m

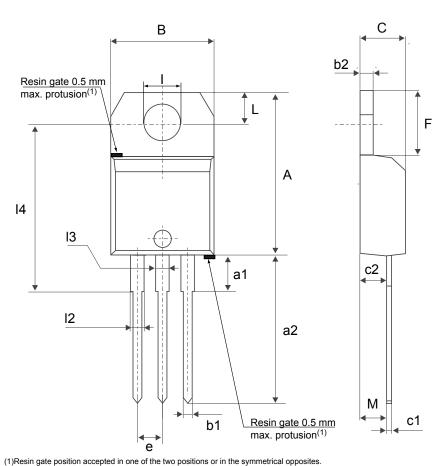


Figure 13. TO-220AB package outline

(Threshing date position accepted in one of the two positions of in the symmetrical opposites

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Table 5. TO-220AB package mechanical data

			D	imensions		
Ref.		Millimeters				
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	15.20		15.90	0.5984		0.6260
a1		3.75			0.1476	
a2	13.00		14.00	0.5118		0.5512
В	10.00		10.40	0.3937		0.4094
b1	0.61		0.88	0.0240		0.0346
b2	1.23		1.32	0.0484		0.0520
С	4.40		4.60	0.1732		0.1811
c1	0.49		0.70	0.0193		0.0276
c2	2.40		2.72	0.0945		0.1071
е	2.40		2.70	0.0945		0.1063
F	6.20		6.60	0.2441		0.2598
ı	3.73		3.88	0.1469		0.1528
L	2.65		2.95	0.1043		0.1161
12	1.14		1.70	0.0449		0.0669
13	1.14		1.70	0.0449		0.0669
14	15.80	16.40	16.80	0.6220	0.6457	0.6614
M		2.6			0.1024	

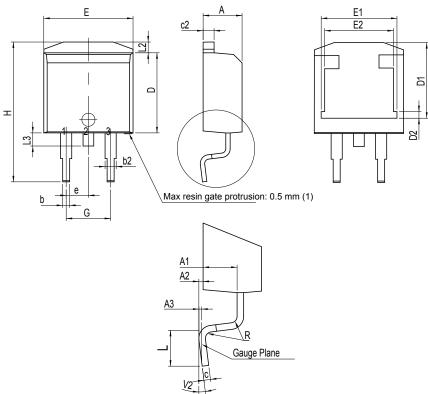
<sup>1.</sup> Inch dimensions are for reference only.

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# 2.2 D<sup>2</sup>PAK package information

Figure 14. D²PAK package outline



(1) Resin gate is accepted in each of position shown on the drawing, or their symmetrical.

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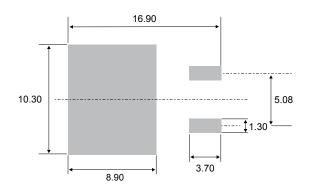


Table 6. D<sup>2</sup>PAK package mechanical data

				Dimensions			
Ref.		Millimeters		Inches <sup>(1)</sup>			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	4.30		4.60	0.1693		0.1811	
A1	2.49		2.69	0.0980		0.1059	
A2	0.03		0.23	0.0012		0.0091	
A3		0.25			0.0098		
b	0.70		0.93	0.0276		0.0366	
b2	1.25		1.7	0.0492		0.0669	
С	0.45		0.60	0.0177		0.0236	
c2	1.21		1.36	0.0476		0.0535	
D	8.95		9.35	0.3524		0.3681	
D1	7.50		8.00	0.2953		0.3150	
D2	1.30		1.70	0.0512		0.0669	
е	2.54			0.1			
Е	10.00		10.28	0.3937		0.4047	
E1	8.30		8.70	0.3268		0.3425	
E2	6.85		7.25	0.2697		0.2854	
G	4.88		5.28	0.1921		0.2079	
Н	15		15.85	0.5906		0.6240	
L	1.78		2.28	0.0701		0.0898	
L2	1.27		1.40	0.0500		0.0551	
L3	1.40		1.75	0.0551		0.0689	
R		0.40			0.0157		
V2	0°		8°	0°		8°	

<sup>1.</sup> Dimensions in inches are given for reference only

Figure 15. D<sup>2</sup>PAK recommended footprint (dimensions are in mm)

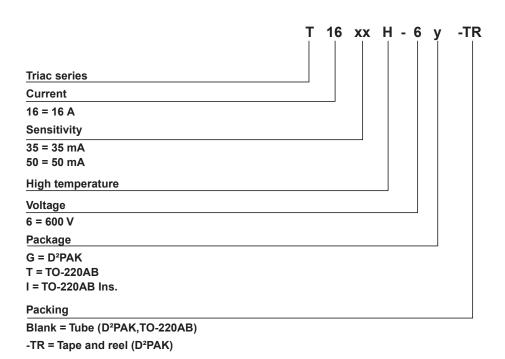


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# 3 Ordering information

Figure 16. Ordering information scheme



**Table 7. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T16xxH-6G	T16xxH 6G	D²PAK	150	50	Tube
T16xxH-6G-TR	T TOXXH 0G	Γ16xxH 6G D²PAK 1.5 g 1000	1000	Tape and reel 13"	
T16xxH-6T	T16xxH 6T	TO-220AB	2.3 g	50	Tube
T16xxH-6I	T16xxH 6I	TO-220AB Ins.	2.3 g	50	Tube

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# **Revision history**

Table 8. Document revision history

Date	Version	Changes
29-May-2007	1	First issue.
20-Sep-2011	2	Updated: Features, Description and Figure 2.
31-Jan-2014	3	Updated Figure 2, Figure 3, Figure 4, Table 2 and Table 5.
23-Mar-2020	4	Updated Table 1. Absolute maximum ratings (limiting values) and Figure 3. On-state RMS current versus ambient temperature.



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